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Ex. Andre' Stevenson

USPT

((4411982)and electrochemical\$2 near (plate\$2 or plating\$2) near (tool\$2 or device\$2 or apparatus\$2)and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2)) and (thick\$2 or thickness\$2) and (test\$2 or testing)

USPT

((4411982)and electrochemical\$2 near (plate\$2 or plating\$2) near (tool\$2 or device\$2 or apparatus\$2) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2)

USPT

(4411982) and electrochemical\$2 near (plate\$2 or plating\$2) near (tool\$2 or device\$2 or apparatus\$2)

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4411982

USPT

(6433561) and CMP and pad\$2 and speed\$2 and pressure\$2

USPT

(6197604) and CMP and pad\$2 and speed\$2 and pressure\$2

USPT

(5966312) and CMP and pad\$2 and speed\$2 and pressure\$2

USPT

(6230069) and CMP and pad\$2 and speed\$2 and pressure\$2ear surface\$2- 6230069) and CMP and pad\$2 and speed\$2

USPT

(6230069) and CMP and pad\$2

USPT

(electrochemical\$2 near (plate\$2 or plating\$2) near (tool\$2 or device\$2 or apparatus\$2) and (thick\$2 or thickness\$2)

USPT

electrochemical\$2 near (plate\$2 or plating\$2) near (tool\$2 or device\$2 or apparatus\$2)

USPT

(6433561) and bath\$2

USPT

(((((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)))and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2))and bath\$2)and (thick\$2 or thickness\$2)) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2) near (tool\$2 or device\$2 or apparatus\$2)

USPT

((((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)))and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2))and bath\$2) and (thick\$2 or thickness\$2)

USPT

((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)))and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2)) and bath\$2

USPT

(6433561) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2)

USPT

(6197604) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2)

USPT

(5966312) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2) 5966312

USPT
(6230069) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2) USPT
6230069

USPT
(((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2)) and CMP and electrochemical\$2 near (plate\$2 or plating\$2) USPT
(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and CMP and electrochemical\$2 near (plate\$2 or plating\$2)

USPT
((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (electrolytic\$3 or electrochemical\$2 or electrolyte\$2) USPT
(6197604) and bath\$2

USPT
(5966312) and bath\$2 USPT
(6230069) and bath\$2

USPT
(6433561) and (electrolytic\$3 or electrochemical\$2) USPT
(6197604) and (electrolytic\$3 or electrochemical\$2)

USPT
(5966312) and (electrolytic\$3 or electrochemical\$2) USPT
(6230069) and (electrolytic\$3 or electrochemical\$2)

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(6230069) and (electrolytic\$3 or electrochemical\$2) USPT
6433561

USPT
6197604 USPT
(((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (monitoring or monitor\$2 or controlling) near

(manufacturing or fabrication\$2)) and (test\$2 or testing) near (workpiece\$2 or tool\$2)

USPT
(6230069) and (test\$2 or testing) near (workpiece\$2 or tool\$2)

USPT
6230069

USPT
((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2))and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2)) and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2)

USPT
(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2)

USPT
((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2))and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2)) and (etch\$2 or etching) and chamber\$2 and CMP

USPT
(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2)

USPT
((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2))and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2)) and (monitoring or monitor\$2) near (manufacturing or fabrication\$2)

USPT

((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2))and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2))and pad\$2) and (processes or processing) near (tool\$2 or workpiece\$2)

USPT
((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2))and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2)) and pad\$2

USPT
(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2)

USPT
(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2)

USPT
(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (etch\$2 or etching) and chamber\$2 and CMP and electrochemical\$2 near (plating or plate\$2)

USPT
(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2)) and (etch\$2 or etching) near chamber\$2 and CMP and electrochemical\$2 near (plating or plate\$2)